







Click here fo	r the 3D	model.
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Click here for the 3D model.		
Dimensions		
L	3.5mm +/-0.3mm	
W	2.6mm +/-0.3mm	
Т	6.15mm +/-0.15mm	
В	0.8mm +/-0.15mm	
Packaging Specifications		

Packaging Specifications	
Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	300

General Information	
Series	KPS SMD Auto X8L HT150C
Style	Stacked Chip
Description	SMD, MLCC, Stacked, Double Chip, High Temperature, Automotive Grade
Features	High Temperature, Automotive Grade
RoHS	Yes
Termination	Tin
Qualifications	AEC-Q200
AEC-Q200	Yes
Typical Component Weight	290 mg
Chip Size	1210-2
Shelf Life	78 Weeks
MSL	1

Specifications	
Capacitance	1uF
Measurement Condition	1 kHz 1.0Vrms
Tolerance	20%
Voltage DC	50 VDC
Dielectric Withstanding Voltage	125 VDC
Temperature Range	-55/+150°C
Temp. Coefficient	X8L
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	+15% (-55C to +125C), +15/-40% (125C to 150C), 1kHz 1.0Vrms
Dissipation Factor	2.5% 1 kHz 1.0Vrms
Aging Rate	3% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	500 MOhms

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

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